

ECX-5947-20.480M TR

[Click part number to visit Part Number Details page](#)

REGULATORY COMPLIANCE (Data Sheet downloaded on Jun 20, 2019)



PLEASE NOTE: Due to the inherent proprietary nature of custom part numbers, certain parameters are intentionally excluded from this specification sheet.

ELECTRICAL SPECIFICATIONS

Nominal Frequency	20.480MHz
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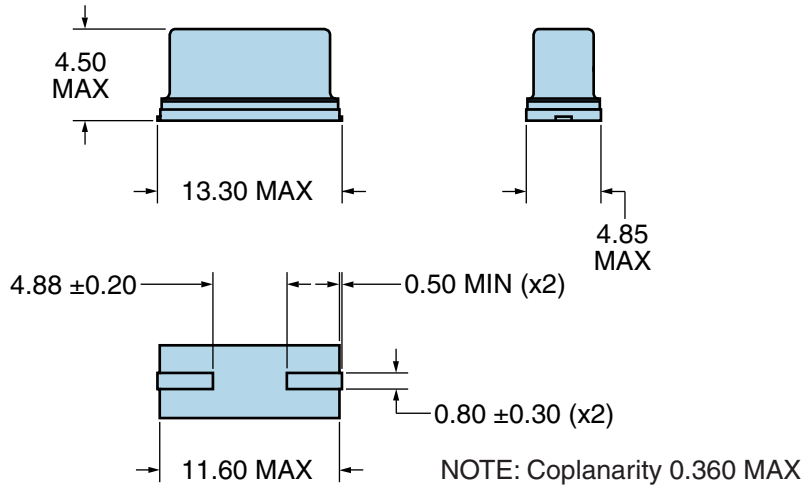
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014 Condition A
Gross Leak Test	MIL-STD-883, Method 1014 Condition C
Mechanical Shock	MIL-STD-202, Method 213 Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007 Condition A

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MECHANICAL DIMENSIONS (all dimensions in millimeters)

LINE	MARKING
1	ECX5947



Suggested Solder Pad Layout

All Dimensions in Millimeters

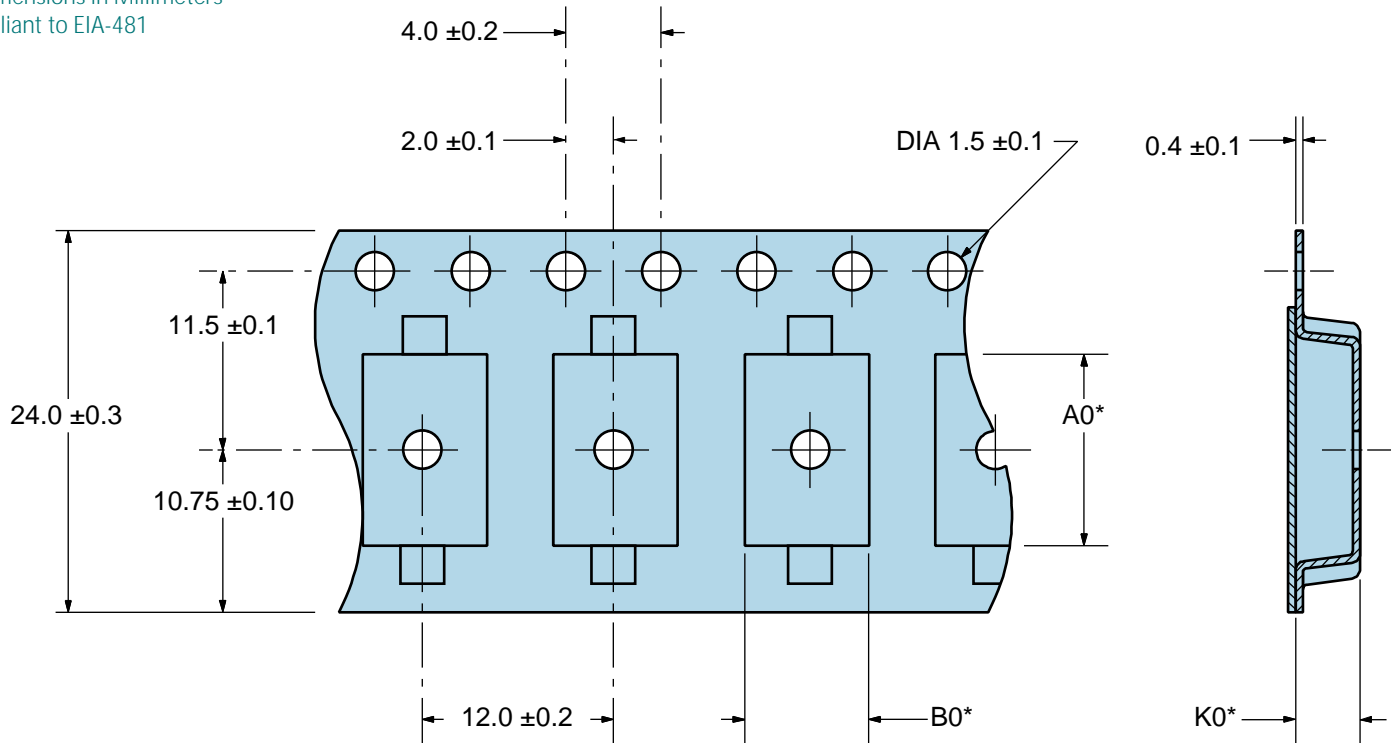


All Tolerances are ±0.1

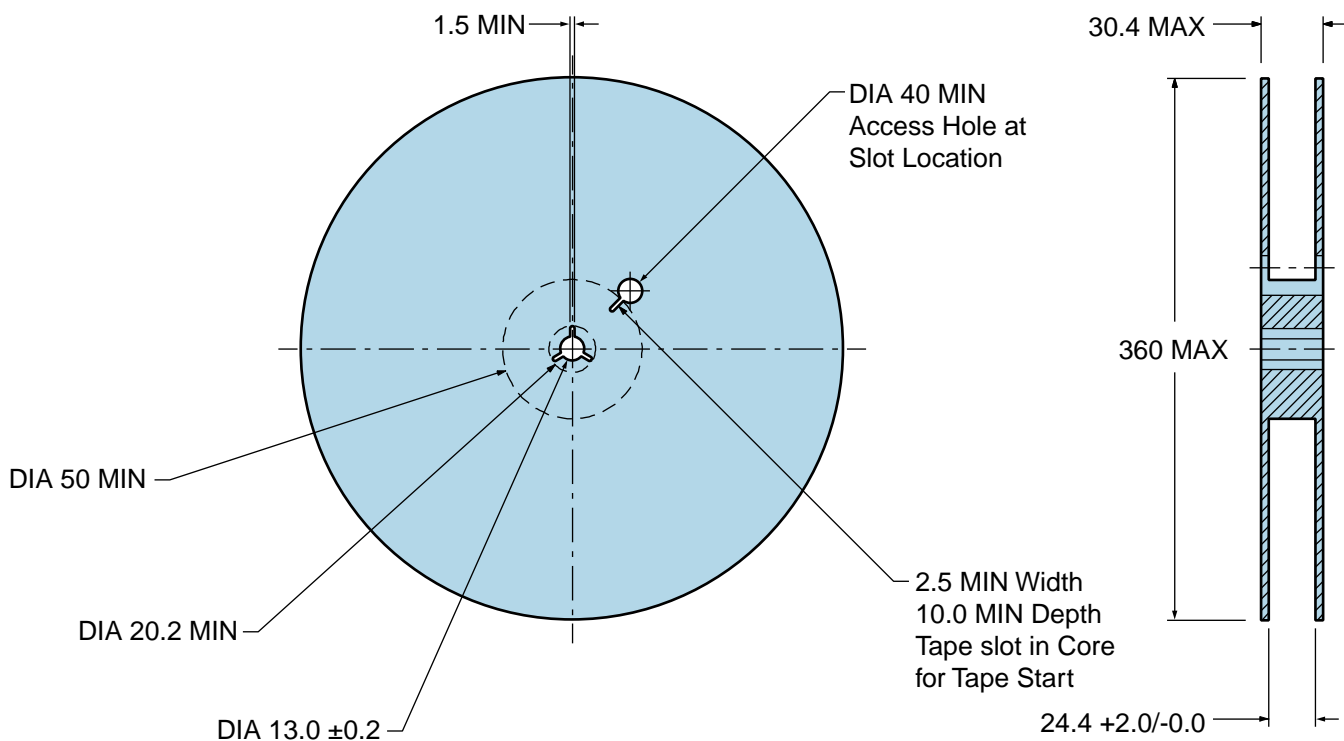
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Tape & Reel Dimensions

Quantity Per Reel: 1,000 units
 All Dimensions in Millimeters
 Compliant to EIA-481



*Compliant to EIA 481A



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Recommended Solder Reflow Methods



High Temperature Infrared/Convection

$T_s \text{ MAX to } T_L$ (Ramp-up Rate)	3°C/Second Maximum
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Preheat

- Temperature Minimum ($T_s \text{ MIN}$)	150°C
- Temperature Typical ($T_s \text{ TYP}$)	175°C
- Temperature Maximum ($T_s \text{ MAX}$)	200°C
- Time ($t_s \text{ MIN}$)	60 - 180 Seconds

Ramp-up Rate (T_L to T_p)	3°C/Second Maximum
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Time Maintained Above:

- Temperature (T_L)	217°C
- Time (t_L)	60 - 150 Seconds

Peak Temperature (T_p)	260°C Maximum for 10 Seconds Maximum
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Target Peak Temperature ($T_p \text{ Target}$)	250°C +0/-5°C
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Time within 5°C of actual peak (t_p)	20 - 40 Seconds
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Ramp-down Rate	6°C/Second Maximum
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Time 25°C to Peak Temperature (t)	8 Minutes Maximum
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Moisture Sensitivity Level	Level 1
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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 245°C

Ts MAX to Tl (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	30 - 60 Seconds
Ramp-up Rate (Tl to Tp)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (Tl)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (Tp)	245°C Maximum
Target Peak Temperature (Tp Target)	245°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (tp)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.